

**REMARKS**

Claims 11 - 20 are pending in the present application. By this Amendment, claim 12 has been amended to correct a minor informality. No new matter has been added. It is respectfully submitted that this Amendment is fully responsive to the Office Action dated August 8, 2005.

**Claim Objections:**

Claims 12, 15, 18 and 20 stand objected to for the specific reasons set forth in item 2 of the Action.

With regard to claims 12 and 18, it is respectfully submitted claim 12 has been amended to overcome this portion of the objection.

With regard to claim 15, it is respectfully submitted that claim 11 recites in lines 5-6, *said organic insulating layer is removed over entire surface thereof so as to provide a planarized surface until a top of said columnar pattern is exposed*, which provides proper antecedent basis for language *the exposed top surface of said columnar pattern*, recited in claim 15.

With regard to claim 20, it is respectfully submitted that claim 11 recites in line 4, *an organic insulating layer is formed* which provides proper antecedent basis for the language *the formation of said organic insulating layer*, recited in claim 20.

Accordingly, withdrawal of the objection to the claims is respectfully requested.

**Drawings:**

In item 3 of the Action, the Examiner asserts that there is no description of layers 6 and 22 in figures 6 and 10, respectively.

However, it is respectfully submitted that the Examiner's position is overcritical, since with reference to Fig. 6, the present specification on page 10, lines 20-31 calls for:

As shown in Fig. 6 ... in this way, since the side faces of the component mounting pad 1 electrically connected to a conductive via 6 formed in the mounted circuit substrate 1 are covered with the organic insulating layer 5.

Further, with reference to Fig. 10, the present specification in the bridging paragraph between pages 19-20 calls for:

FIG. 10 is a schematic cross-sectional view ... then an electroless Ni plated layer 22 with a maximum thickness of 3  $\mu$  m, for example, 2.0  $\mu$  m, is formed by electroless plating, and immediately after that, an electroless Au plated layer 21 with a maximum thickness of 1 u.m, for example, 0.3  $\mu$  m, is formed by electroless plating.

Accordingly, withdrawal of the objection to the drawings is respectfully requested.

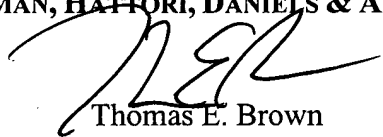
In view of the aforementioned amendments and accompanying remarks, Applicants submit that that the claims, as herein amended, are in condition for allowance. Applicants request such action at an early date.

Response After Final  
Serial No. 10/784,740  
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If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,  
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